



MAIL STOP ISSUE FEE  
PATENT  
8017-1122

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Noriaki ODA

Conf. 2345

Application No. 10/761,204

Group 2826

Filed January 22, 2004

Examiner A. Williams

SEMICONDUCTOR DEVICE WITH BONDING PAD  
SUPPORT STRUCTURE

**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In compliance with Rules 1.97 and 1.98, and in fulfillment of the duty of disclosure under Rule 1.56, the accompanying document, a copy of which is attached to this statement, is made of record on the enclosed Form PTO-1449.

A concise explanation of the relevance of this item is that this reference was cited by the Japanese Patent Office in an Official Action. A copy of the Japanese Official Action in which it was cited is attached hereto, with what is believed to be the pertinent portion enclosed in a wavy line. **An English translation of the enclosed portion is also attached hereto.** JP 2001-015516 and JP 2001-267323 were previously cited in the Information Disclosure Statement filed January 22, 2004.

Under the provisions of 37 CFR 1.97(e), the undersigned hereby certifies that each item of information con-

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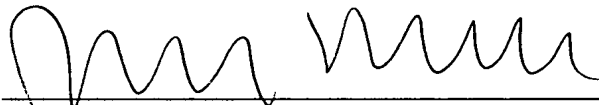
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tained in this Information Disclosure Statement was first cited in any communication from a foreign Patent Office in a counterpart foreign application not more than three months prior to the filing of this Statement.

Please charge the fee of \$180 required by 37 CFR 1.17(p) to our credit card as set forth on the attached Credit Card Payment Form.

Respectfully submitted,

YOUNG & THOMPSON

A handwritten signature in black ink, appearing to read 'R. J. Patch', written over a horizontal line.

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November 28, 2007